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PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2000-159828

(43)Date of publication of application : 13.06.2000

(51)Int.Cl.

C08F 2/48
C08F 2/54
C08F290/00
C09D 4/06
G03F 7/004
G03F 7/028
G03F 7/038
G03F 7/20

(21)Application number : 10-340141

(22)Date of filing : 30.11.1998

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(54) PHOTSENSITIVE RESIN COMPOSITION, ELECTRON-BEAM-CURABLE RESIN
COMPOSITION, AND THEIR CURED ITEMS

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a photosensitive resin composition which cures quickly and gives a cured item excellent in adhesiveness, external appearance, and chemical resistance and having high surface hardness and strengths by compounding (A) a polymerizable (meth) acrylic syrup comprising (A1) a (meth) acrylic polymer having polymerizable double bonds and prepared by using a compound containing at least one metal selected from among Zn, Sn, and Zr, as a catalyst, and (A2) a polymerizable monomer with (B) a photopolymerization initiator.

SOLUTION: The (meth)acrylic polymer having polymerizable double bonds is a polymer formed by reacting a (meth)acrylic polymer having carboxyl groups with a polymerizable unsaturated epoxy compound and/or a polymer formed by reacting a (meth)acrylic polymer having epoxy groups with a polymerizable unsaturated acid compound. The compound containing at least one metal selected from among Zn, Sn, and Zr is a catalyst for the reaction of carboxyl groups with epoxy groups and is used for accelerating the introduction of polymerizable double bonds. Examples of the catalyst include Zn octanoate, Sn octanoate, and Zr octanoate.